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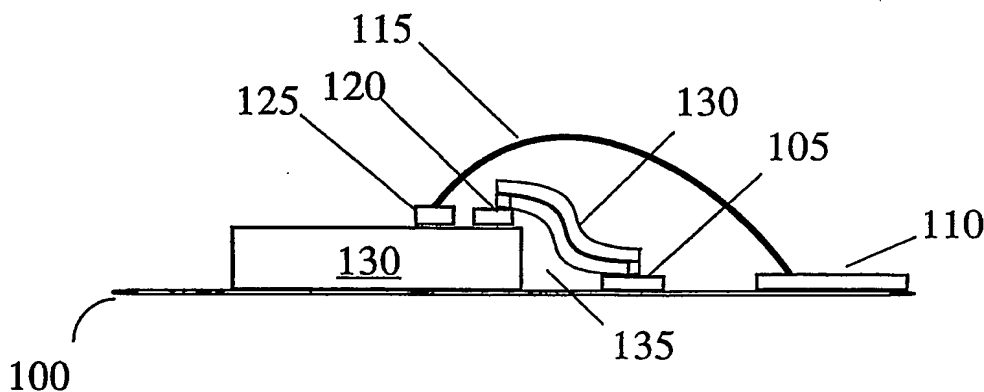
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(54) Title: HIGH DENSITY PACKAGE INTERCONNECT POWER AND GROUND STRAP AND METHOD THEREFOR



(57) Abstract: One aspect of the present invention relates to reducing the impedance of the paths connecting the power or ground of a device and a BGA package. In a particular example implementation, impedance of the signal bond wires is controlled by placing a ground strap (130) at a predetermined distance from the signal bond wires (115). In a related example embodiment, a low impedance power or ground connection is made between a device die (140) and package in close proximity to wire bonds (115). An integrated circuit (140) includes a plurality of grounding pads, signal pads, power pads and a package for mounting the integrated circuit. The package (100) comprises a plurality of pad landings (110), a grounding ring (105) surrounding the integrated circuit (140); and a grounding strap (130) coupling the grounding ring (105) to the grounding pads (120) of the integrated circuit.